



THE DATASHEET OF HS1J



Features

- Glass passivated junction chip
- For surface mounted application
- Low forward voltage drop
- Low profile package
- Built-in stain relief, ideal for automatic placement
- Fast switching for high efficiency
- High temperature soldering: 260°C/10 seconds at terminals
- Plastic material used carries underwriters laboratory classification 94V-0



DO-214AC (SMA)

Mechanical Data

- Cases: Molded plastic
- Terminals: Solder plated
- Polarity: Indicated by cathode band
- Weight: 0.064 gram typical

Maximum Ratings & Electrical Characteristics (T_A=25°C unless otherwise specified)

Parameter	Symbol	HS1A	HS1B	HS1D	HS1F	HS1G	HS1J	HS1K	HS1M	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	300	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current See Fig.1	I _(AV)	1.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30								A
Maximum Instantaneous Forward Voltage @ 1.0A	V _F	1.0				1.3	1.7			V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	5.0								uA
	T _A =125°C	150								
Maximum Reverse Recovery Time ¹	t _{rr}	50					75			nS
Typical Junction Capacitance ²	C _J	20					15			pF
Operating Junction Temperature Range	T _J	-55 to +150								°C
Storage Temperature Range	T _{STG}	-55 to +150								°C

Notes:

1. Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V

Thermal Characteristics

Parameter	Symbol	HS1A	HS1B	HS1D	HS1F	HS1G	HS1J	HS1K	HS1M	Unit
Typical Thermal Resistance ³	R _{θJA}	72								°C/W
	R _{θJC}	33								
	R _{θJL}	7								

Notes:

3. The thermal resistance from junction to ambient, case and lead, mounted on FR-4 P.C.B with 5×5mm copper pads.

Ratings and Characteristics Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

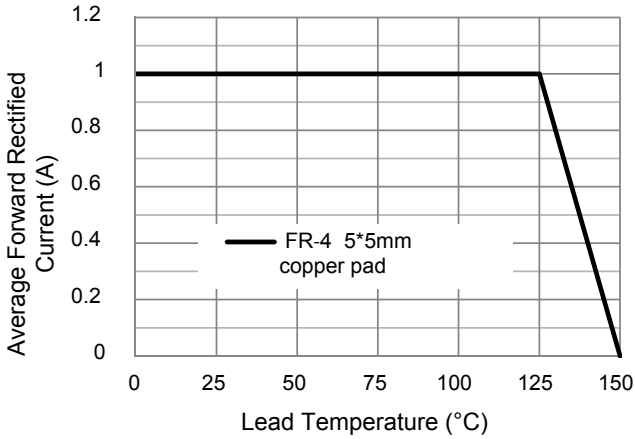


Figure 1. Forward Current Derating Curve

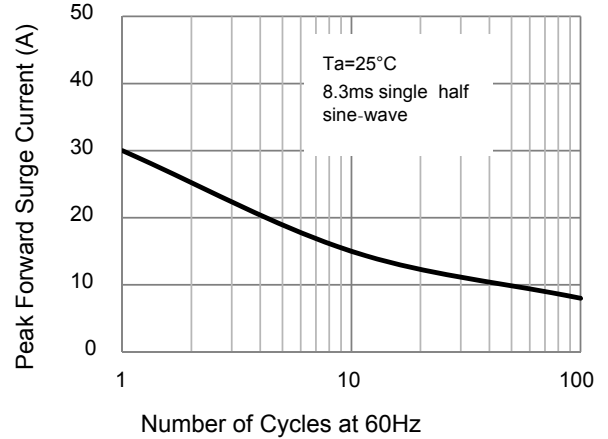


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

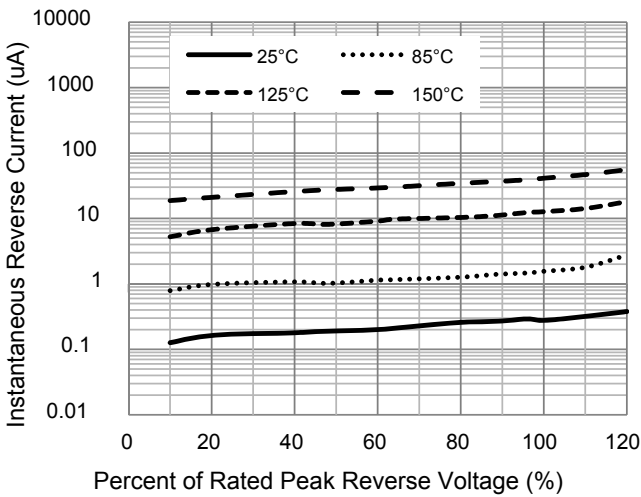


Figure 3. Typical Reverse Characteristics

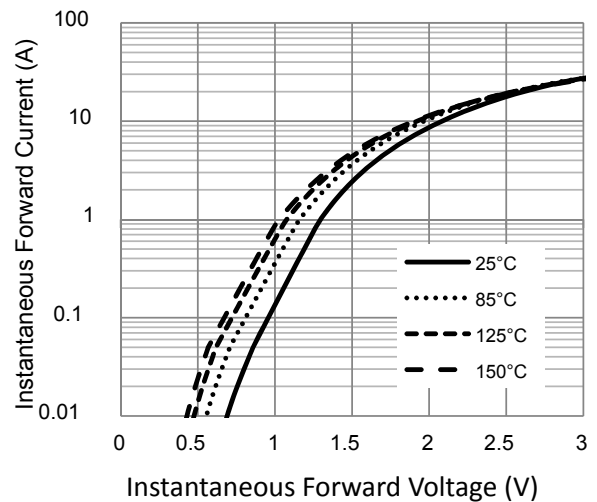


Figure 4. Typical Forward Characteristics (HS1J-M)

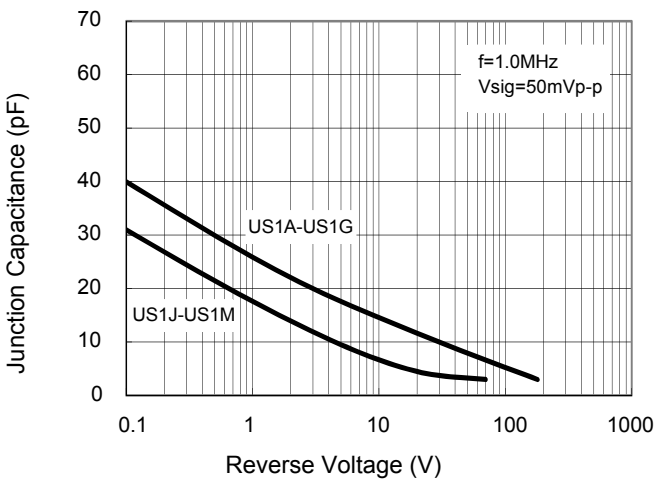


Figure 5. Typical Junction Capacitance

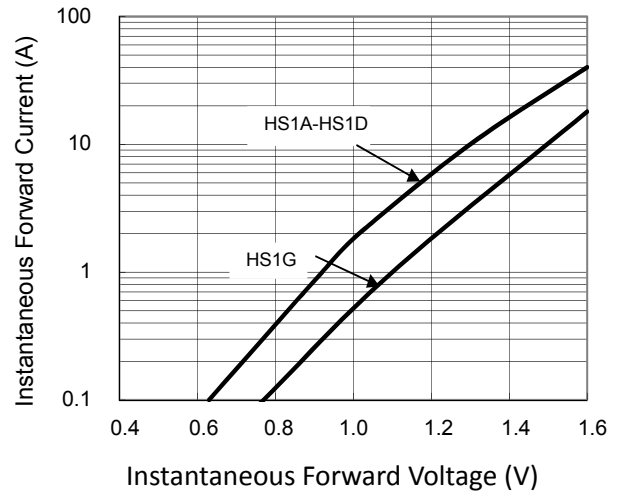


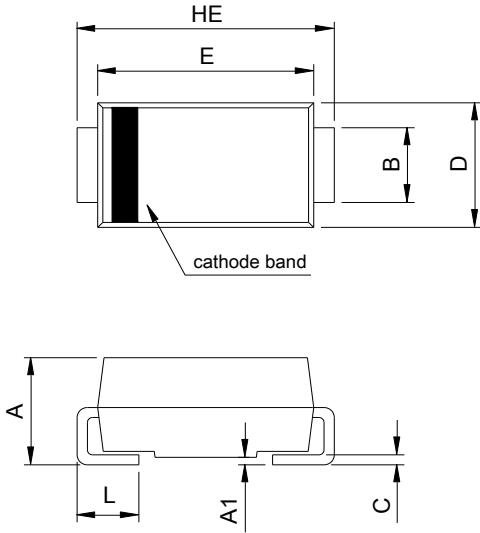
Figure 6. Typical Forward Characteristics (HS1A-G)

HS1A thru HS1M

Ultrafast Recovery Rectifiers

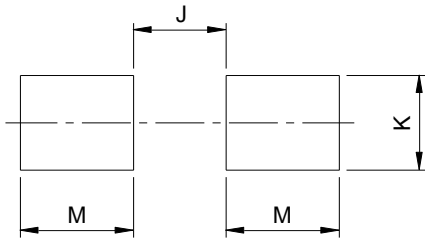
Reverse Voltage 50V to 1000V Forward Current 1.0 A

Package Outline Dimensions DO-214AC (SMA)



DIM	SMA (DO-214AC)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.90	2.30	0.075	0.091
A1	0.00	0.20	0.000	0.008
B	1.25	1.65	0.049	0.065
C	0.15	0.31	0.006	0.012
D	2.35	2.90	0.093	0.114
E	3.99	4.60	0.157	0.181
HE	4.80	5.30	0.189	0.209
L	0.76	1.52	0.030	0.060

Recommended Pad Layout



DIM	Recommended Pad Layout (Reference ONLY)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.20	-	0.087
K	1.72	-	0.068	-
M	2.00	-	0.079	-

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